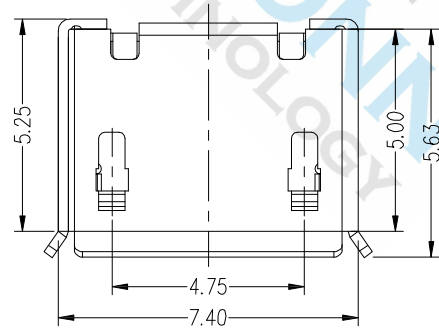


P.C.B LAYOUT MOUNTING PATTERN



NOTES:

MATERIAL:

- 1.1 HOUSING: LCP,UL94V-0
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS

Finish:

- 2.1 Contact: Plated Gold in Mating Area ;  
Gold Plated on Solder Balls  
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.0 A MAX
- 3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 50 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

DIMENSIONS TOLERANCE METRIC .0±±0.30 .00±±0.20 .000±±0.10 ANG.=±2°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審校(CH'K)	Calvin	圖名(NAME) MICRO USB2.0 B TYPE R/A SMT+DIP 6.4mm 後貼無柱	WISCONN Technology Co., Ltd Tel:02-2790-1979 Fax:02-2790-1569									
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena								料號(PART NUMBER)	WMRU2-5-xxMTR3D4		
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期 DATE)	JUL.27.2017	圖號(DRAW NUMBER)	T002	圖檔(FILE NAME .DWG)		比例 (SCALE)	1/1	圖紙 (SIZE)	A4	頁次 (SHEET)	1	版次 (REV.)